Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP FF 12904E Switch Chassis(JH262A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove all of the labels 2.
2. Unscrew the screws on angle 3, and then remove angle 3.
3. Unscrew the screws on the blank panel 4&5&6, and then remove the blank panel 4&5&6.
4. Remove the power blank panel 7.
5. Unscrew the screws on the wire bracket 8, and then remove the wire bracket 8.
6. Remove part 8-2 form part 8-1.
7. Remove part 8-3 form part 8-2.
8. Remove part 9 form subrack 10.
9. Unscrew the screws on chassis 1 and part 12, and then remove subrack 10.
10. Unscrew the screws on part 11, and then remove part 11.
11. Unscrew the screws on the PCB 12, and then remove the PCB 12.
12. Remove insulating plate 11-2 form part 11-1.
13. Unscrew the screws on the PCB 12-1, and then remove guide pin 12-2.
14. Remove part 13 from chassis 1.
15. Unscrew the screws on chassis 1, and then remove rib 14.
16. Remove insulating plate 14-2 from rib 14-1.
17. Remove insulating plate 15 from chassis 1.
18. Unscrew the screws on PCB 13-1, and then remove PCB 13-1 from part 13-2.
19. Unscrew the screws on PCB 13-1, and then remove the guide 13-3 from PCB 13-1.
20. Remove shielding fingers 4-2&5-2&7-2 and films 4-3&5-3 from the blank panel 4&5&7.
21. Unscrew the screws on part 6-2, and then remove part 6-2.
22. Unscrew the screws on blank panel 6-1, and then remove part 6-3&6-4.
23. Unscrew the screws on part 6-4-1, and then remove part 6-4-1&6-4-2&6-4-3.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

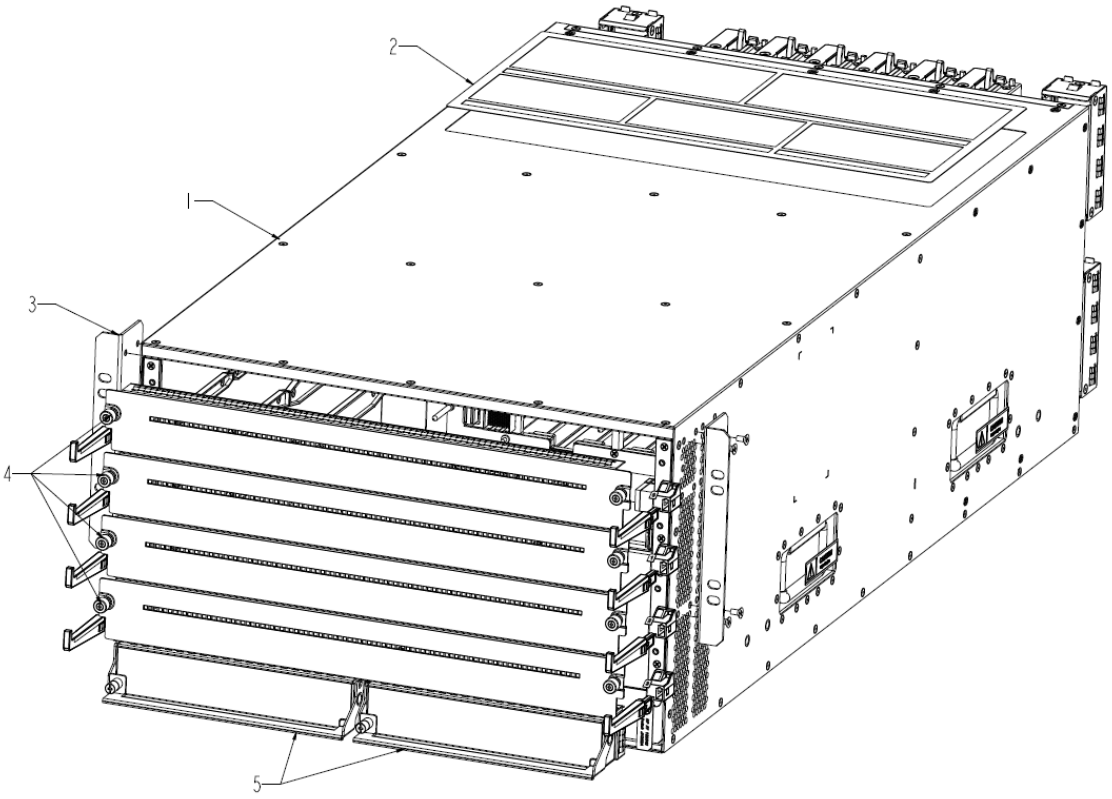

Figure 1Treatments to the product（front view）

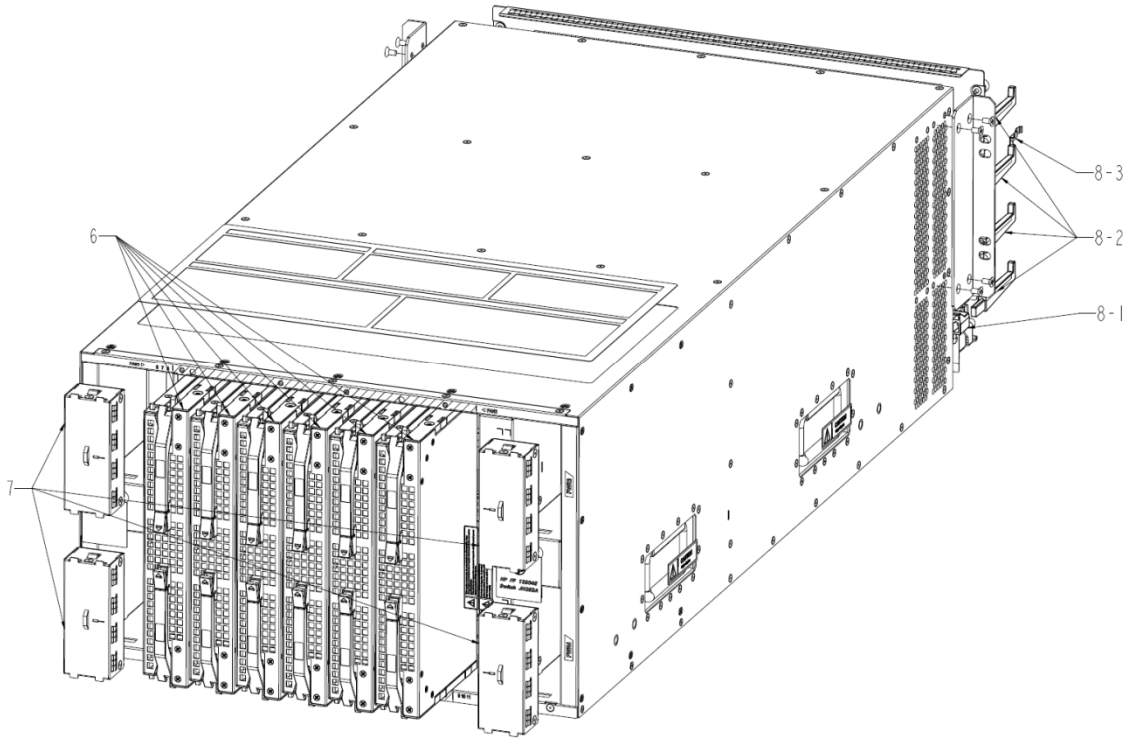

Figure 2 Treatments to the product (rear view)

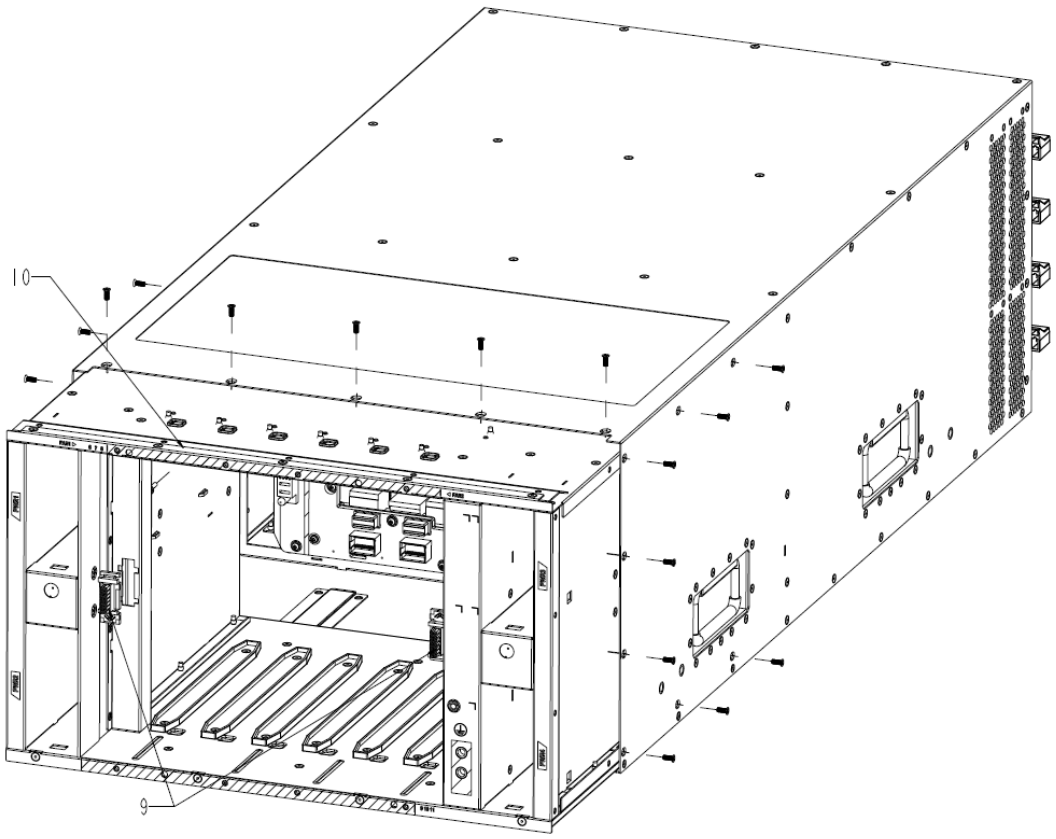

Figure 3 Treatments to the product (rear view)

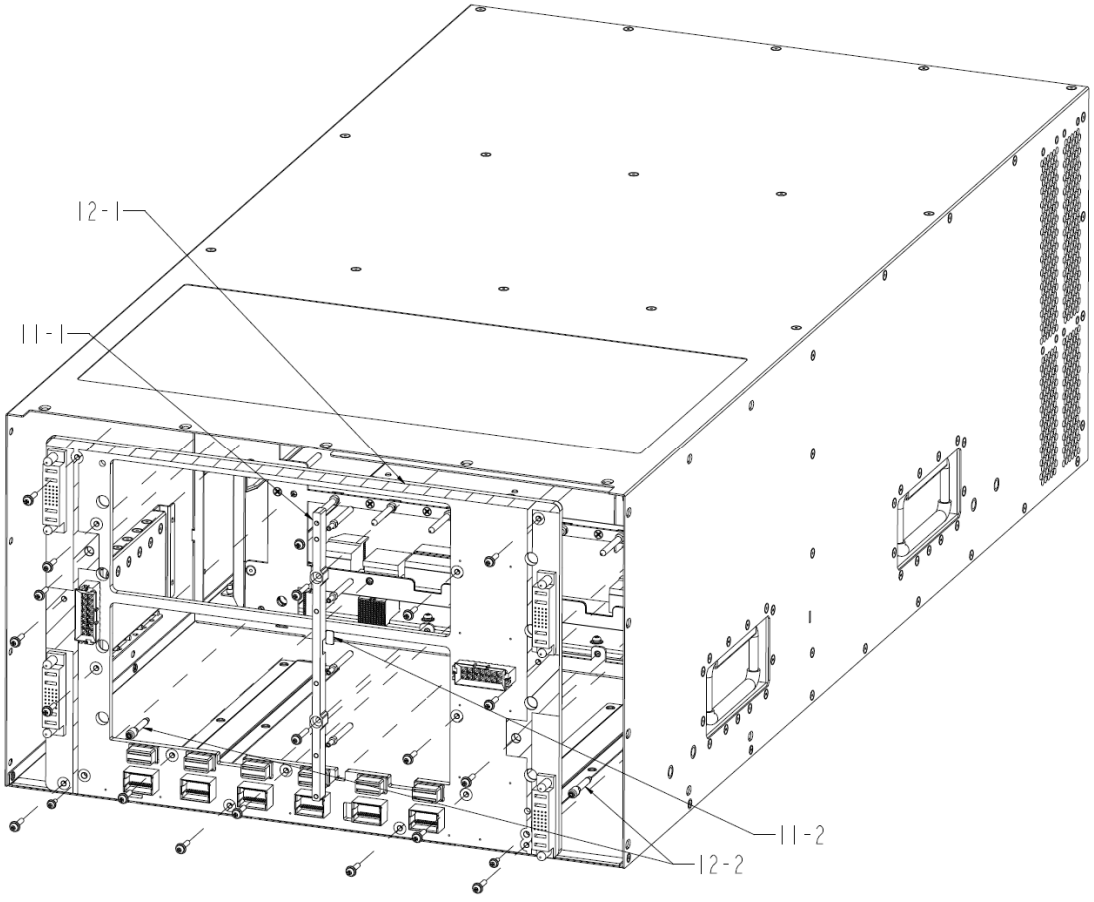

Figure 4 Treatments to the PCB

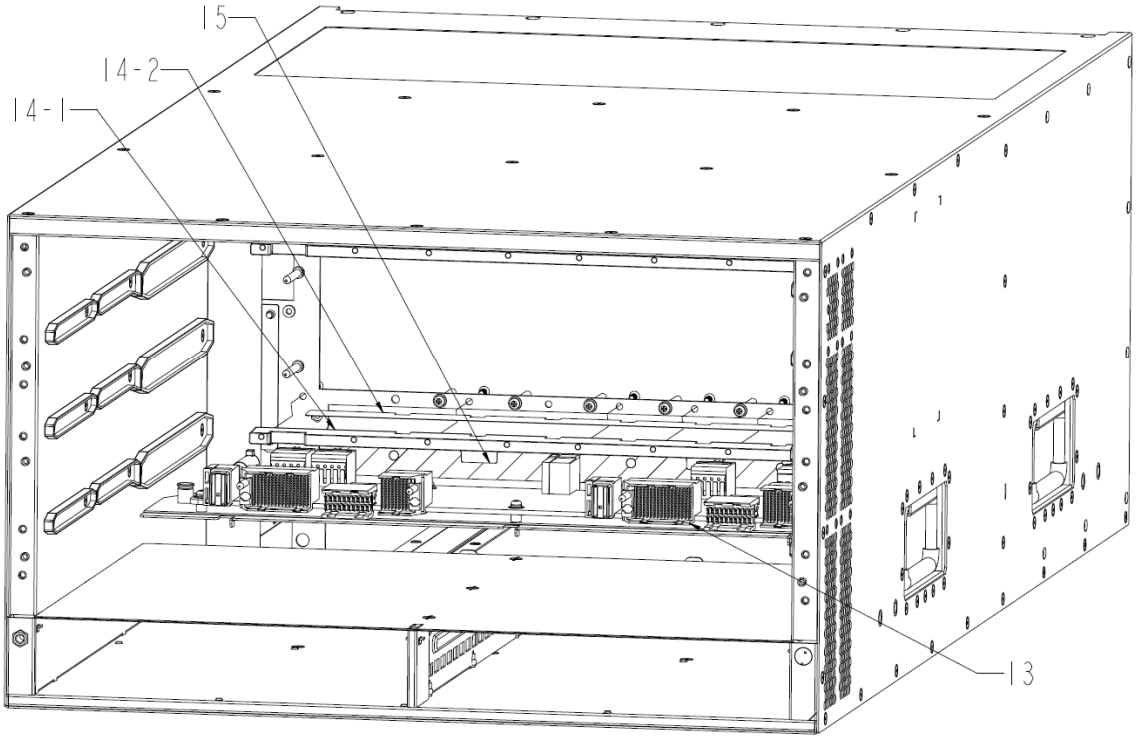

Figure 5 Treatments to the product（front view）

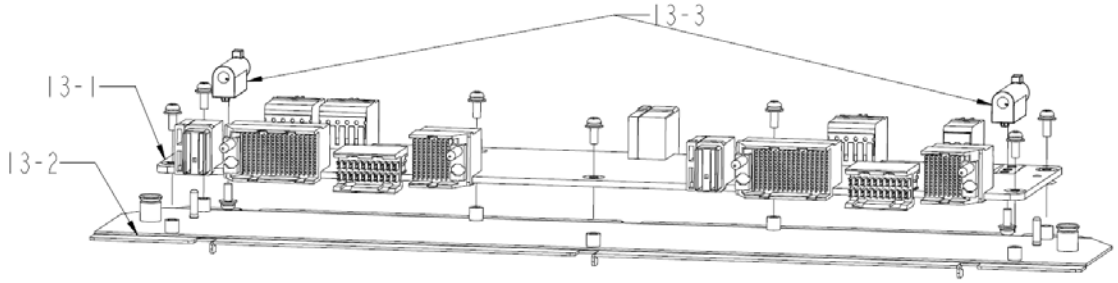

Figure 6Treatments to part 13

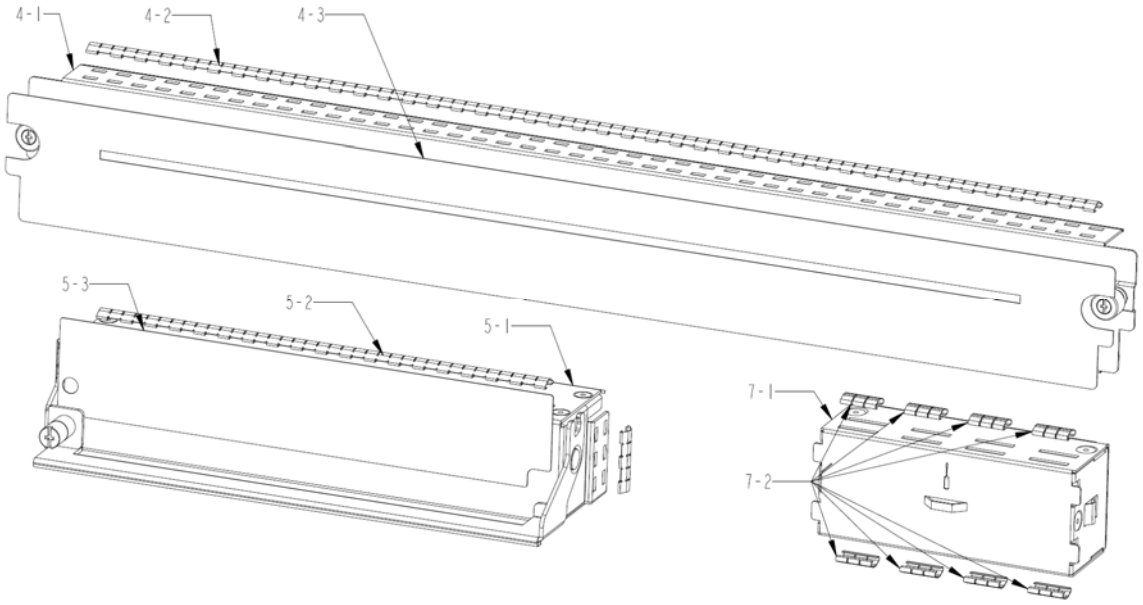

Figure 7 Treatments to blank panel

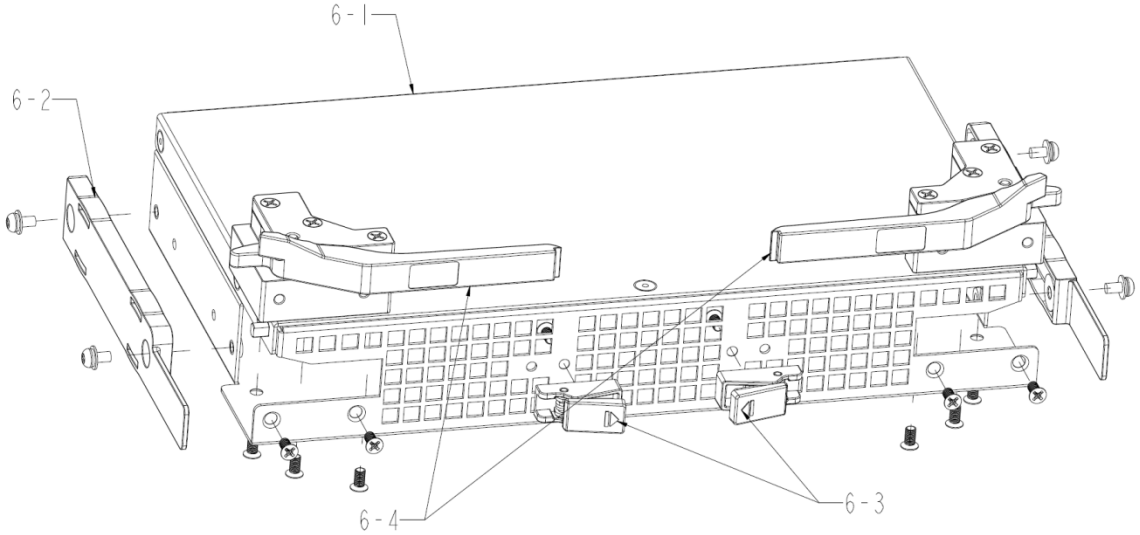

Figure 8 Treatments to blank panel

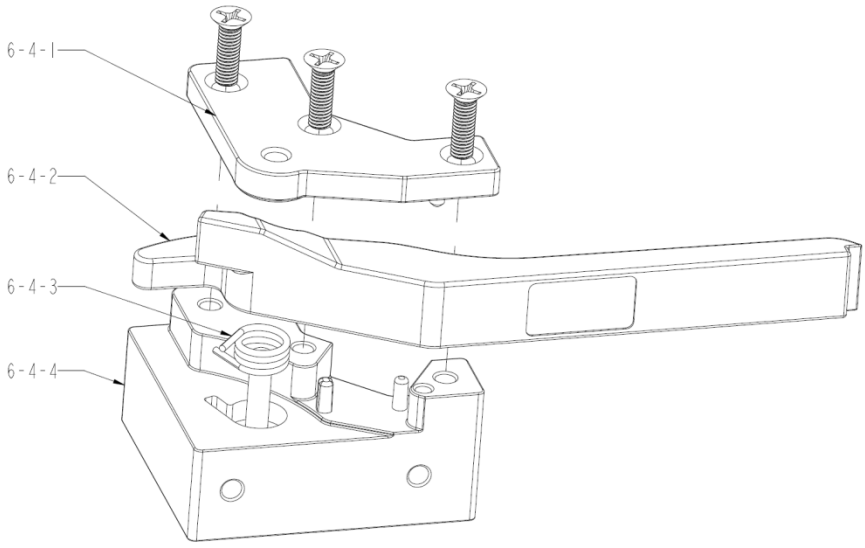

Figure 9Treatments to prat 6-4

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	6376.0	24.34%		Fe recycling
2		PC	19.9	0.07%		Pla recycling
3		Fe	340.4	1.29%		Fe recycling
4	4-1	Fe	237.2*4	3.62%		Fe recycling
	4-2	Be-Cu	3.0*4	0.04%		Cu recycling
	4-3	PC	5.7*4	0.08%		Pla recycling
5	5-1	Fe	300.0*2	2.29%		Fe recycling
	5-2	Be-Cu	1.0*2	0.01%		Cu recycling
	5-3	PC	2.1*2	0.02%		Pla recycling
6	6-1	Fe	642.8*6	14.72%		Fe recycling
	6-2	PC	14.2*6	0.33%		Pla recycling
	6-3	Zn,Fe	24.0*6	0.55%		Zn recycling Fe recycling
	6-4	Zn,Fe	281.5*6	6.45%		Zn recycling Fe recycling
7	7-1	Fe	86.2*4	1.32%		Fe recycling
	7-2	Be-Cu	0.4*4	0.01%		Cu recycling
8	8-1	Zn	23.9*8	0.73%		Zn recycling
	8-2	Zn	70.1*4	1.07%		Zn recycling
	8-3	Fe	0.5*8	0.02%		Fe recycling
9		PC, Cu	88.6	0.34%		Pla recycling Cu recycling
10		Fe	9134.0	34.86%		Fe recycling
11	11-1	Al	28.6	0.11%		Al recycling
	11-2	PC	0.1	0.01%		Pla recycling
12	12-1	Complex PCB	1220.6	4.65%	The surface of PCB is greater than 10 square centimeters;	
	12-2	Fe	9.0	0.03%		Fe recycling
13	13-1	Complex PCB	283.0	1.07%	The surface of PCB is greater than 10 square centimeters;	
	13-2	Fe	321.3	1.23%		Fe recycling
	13-3	Zn	32.3	0.12%		Zn recycling
14	14-1	Al	78.8*2	0.60%		Al recycling
	14-2	PC	1.2	0.01%		Pla recycling
15		PC	0.6	0.01%		Pla recycling

4.0 Revised record

Date	Version	Author	Modify content
2015.05.20	V0	Zhao Jiawen	Initial version